			DB	Time stamp
L Number	Hits	<pre>Search Text (((((((((((((conduct\$3 copper) near5 (foil</pre>	USPAT;	2003/04/29 18:26
1	2856	sheet layer) ) and (etch\$3 pattern\$4)) and	US-PGPUB	
		(via trench hole recess)) and (insulat\$3		j
		dielectric)) and (pr photo?resist		
		photoresist resist)) and (copper Cu		
		aluminum Al)) and wir\$3) and resin) and		
		circuit) and (cover\$3 encapsulat\$3)) and		
		((etch\$3 pattern\$4) near10 (copper Cu	1	ĺ
	_ :	conduct\$3))) and wir\$3) and (die bond\$3)	EPO; JPO;	2003/04/29 18:27
2	5	(((((((((((((conduct\$3 copper) near5 (foil	DERWENT;	2003/04/29 10:27
		sheet layer) ) and (etch\$3 pattern\$4)) and (via trench hole recess)) and (insulat\$3	IBM TDB	}
		dielectric)) and (pr photo?resist	1211_132	
		photoresist resist)) and (copper Cu		1
		aluminum Al)) and wir\$3) and resin) and		
		circuit) and (cover\$3 encapsulat\$3)) and		)
		((etch\$3 pattern\$4) near10 (copper Cu		
	_	conduct\$3))) and wir\$3) and (die bond\$3)	EDO. TDO.	2002/04/20 10:20
3	5	(((((((((((((conduct\$3 copper) near5 (foil	EPO; JPO;	2003/04/29 18:28
		sheet layer plate) ) and (etch\$3 pattern\$4)) and (via trench hole recess))	DERWENT; IBM TDB	
ļ		and (insulat\$3 dielectric)) and (pr	1001100	
		photo?resist photoresist resist)) and		
		(copper Cu aluminum Al)) and wir\$3) and		
ļ		resin) and circuit) and (cover\$3	1	
		encapsulat\$3)) and ((etch\$3 pattern\$4)		
		near10 (copper Cu conduct\$3))) and wir\$3)		
		and (die bond\$3)	HCDAM.	2003/04/29 18:29
4	2908	<pre>((((((((((((conduct\$3 copper) near5 (foil sheet layer plate) ) and (etch\$3</pre>	USPAT;	2003/04/29 10.29
		pattern\$4)) and (via trench hole recess))	05 10105	
		and (insulat\$3 dielectric)) and (pr		
		photo?resist photoresist resist)) and		
		(copper Cu aluminum Al)) and wir\$3) and		
		resin) and circuit) and (cover\$3		
		encapsulat\$3)) and ((etch\$3 pattern\$4)		İ
		near10 (copper Cu conduct\$3))) and wir\$3)		
_	F.0	and (die bond\$3)	USPAT;	2003/04/29 18:30
5	52	<pre>(((((((((((((conduct\$3 copper) near5 (foil sheet layer plate) ) and (etch\$3</pre>	US-PGPUB	2003/04/29 18.30
		pattern\$4)) and (via trench hole recess))	00 10102	į
		and (insulat\$3 dielectric)) and (pr		
		photo?resist photoresist resist)) and		
		(copper Cu aluminum Al)) and wir\$3) and		
		resin) and circuit) and (cover\$3		
		encapsulat\$3)) and ((etch\$3 pattern\$4)		
		near10 (copper Cu conduct\$3))) and wir\$3) and (die bond\$3)) not		
		and (die bond;3)) not   ((((((((((((conduct\$3 copper) near5		,
		(foil sheet layer) ) and (etch\$3		
		pattern\$4)) and (via trench hole recess))		
j		and (insulat\$3 dielectric)) and (pr		
		photo?resist photoresist resist)) and		
ĺ		(copper Cu aluminum Al)) and wir\$3) and		
		resin) and circuit) and (cover\$3		
		encapsulat\$3)) and ((etch\$3 pattern\$4)		
		<pre>near10 (copper Cu conduct\$3))) and wir\$3) and (die bond\$3))</pre>		
_	12192	and (die bond\$3))   conduct\$3 near5 foil	USPAT;	2003/02/11 15:12
_	12192	Conducto meals for	US-PGPUB	2000,02,11 10.11
- '	4707	(conduct\$3 near5 foil) and resin	USPAT;	2003/02/11 12:50
			US-PGPUB	0000/05/55
-	3142	((conduct\$3 near5 foil) and resin) and	USPAT;	2003/02/11 12:51
	0===	(pattern\$5 etch\$3)	US-PGPUB	2002/02/11 12:51
_	2706	(((conduct\$3 near5 foil) and resin) and	USPAT; US-PGPUB	2003/02/11 12:51
		(pattern\$5 etch\$3)) and (insulat\$3 dielectric)	US-FGFUB	
_	2530	dielectric) ((((conduct\$3 near5 foil) and resin) and	USPAT;	2003/02/11 12:53
	2550	(pattern\$5 etch\$3)) and (insulat\$3	US-PGPUB	
		dielectric)) and (via hole recess contact)		
	L	1		L

				T
_	968	(((((conduct\$3 near5 foil) and resin) and	USPAT;	2003/02/11 12:53
		(pattern\$5 etch\$3)) and (insulat\$3	US-PGPUB	1
		dielectric)) and (via hole recess		
		contact)) and (pr resist)		1
_	755		USPAT	2003/02/11 12:54
	, , ,	(pattern\$5 etch\$3)) and (insulat\$3		
		dielectric)) and (via hole recess		(
		contact)) and (pr resist)		
1_	445		USPAT;	2003/02/11 13:02
	110	marcray or to mode of the second	US-PGPUB	
_	183779	(conduct\$3 copper) near5 (foil sheet	USPAT;	2003/02/11 15:16
_	103773	layer)	US-PGPUB	
	111368	((conduct\$3 copper) near5 (foil sheet	USPAT;	2003/02/11 15:18
_	111300	layer) ) and (etch\$3 pattern\$4)	US-PGPUB	
	80228	(((conduct\$3 copper) near5 (foil sheet	USPAT;	2003/02/11 15:30
_	80228	layer) ) and (etch\$3 pattern\$4)) and (via	US-PGPUB	2000, 02, 22 2112
			05 13105	]
		trench hole recess)	USPAT;	2003/02/11 15:31
-	67836			2003/02/11 13:31
		layer) ) and (etch\$3 pattern\$4)) and (via	US-PGPUB	
		trench hole recess)) and (insulat\$3		
		dielectric)	1	
-	30233	(((((conduct\$3 copper) near5 (foil sheet	USPAT;	2003/02/11 15:32
		layer) ) and (etch\$3 pattern\$4)) and (via	US-PGPUB	
Ì		trench hole recess)) and (insulat\$3		
		dielectric)) and (pr photo?resist	1	1
		photoresist resist)		Į l
_	28811	((((((conduct\$3 copper) near5 (foil sheet	USPAT;	2003/02/11 15:34
		layer) ) and (etch\$3 pattern\$4)) and (via	US-PGPUB	
}		trench hole recess)) and (insulat\$3		1
		dielectric)) and (pr photo?resist		
}	ļ.	photoresist resist)) and (copper Cu	)	]
		aluminum Al)		
j _	13674	1	USPAT;	2003/02/11 15:35
-	130/4	layer) ) and (etch\$3 pattern\$4)) and (via	US-PGPUB	] 2000, 02, 22
		trench hole recess)) and (insulat\$3	05 10105	
		dielectric)) and (pr photo?resist		
1	Į.	photoresist resist)) and (copper Cu		
	5000	aluminum Al)) and wir\$3	HCDAT.	2003/02/11 15:39
-	5322		USPAT; US-PGPUB	2003/02/11 13.33
		sheet layer) ) and (etch\$3 pattern\$4)) and	US-PGPUB	
Ì		(via trench hole recess)) and (insulat\$3	ļ	
		dielectric)) and (pr photo?resist	1	1
1		photoresist resist)) and (copper Cu	1	1
		aluminum Al)) and wir\$3) and resin		2002/00/11 16 25
-	834	((((((((conduct\$3 copper) near5 (foil	USPAT;	2003/02/11 16:35
		sheet layer) ) and (etch\$3 pattern\$4)) and	US-PGPUB	<u> </u>
1		(via trench hole recess)) and (insulat\$3	1	1
		dielectric)) and (pr photo?resist		]
1		photoresist resist)) and (copper Cu	1	]
		aluminum Al)) and wir\$3) and resin) and		
]		(singulat\$3 dic\$3)	J	J
-	4670		USPAT;	2003/02/11 16:36
		sheet layer) ) and (etch\$3 pattern\$4)) and	US-PGPUB	
	{	(via trench hole recess)) and (insulat\$3	{	
		dielectric)) and (pr photo?resist		
		photoresist resist)) and (copper Cu	-	
		aluminum Al)) and wir\$3) and resin) and		1
1		circuit	{	
_	4040	1 7	USPAT;	2003/02/11 16:37
-	4040		US-PGPUB	2003, 02,111 10.31
	1	sheet layer) ) and (etch\$3 pattern\$4)) and (via trench hole recess)) and (insulat\$3	05-FGF0D	į į
			}	
		dielectric)) and (pr photo?resist		
}		dielectric)) and (pr photo?resist photoresist resist)) and (copper Cu		
		dielectric)) and (pr photo?resist		

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	3307	(((((((((conduct\$3 copper) near5 (foil	USPAT;	2003/02/11 17:36
		sheet layer) ) and (etch\$3 pattern\$4)) and	US-PGPUB	
		(via trench hole recess)) and (insulat\$3		
		dielectric)) and (pr photo?resist		
		photoresist resist)) and (copper Cu	1	
		aluminum Al)) and wir\$3) and resin) and		
		circuit) and (cover\$3 encapsulat\$3)) and		
	ĺ	((etch\$3 pattern\$4) near10 (copper Cu		
		conduct\$3))	1	
_	3307	((((((((((conduct\$3 copper) near5 (foil	USPAT;	2003/02/11 17:36
	330,	sheet layer) ) and (etch\$3 pattern\$4)) and	US-PGPUB	
		(via trench hole recess)) and (insulat\$3	05 20102	
		dielectric)) and (pr photo?resist	1	
		photoresist resist)) and (copper Cu		
		aluminum Al)) and wir\$3) and resin) and		
		circuit) and (cover\$3 encapsulat\$3)) and		
		((etch\$3 pattern\$4) near10 (copper Cu	ļ	
		conduct\$3))) and wir\$3	-	
1_	2618	(((((((((((conduct\$3 copper) near5 (foil	USPAT;	2003/02/11 17:39
\	2010	sheet layer) ) and (etch\$3 pattern\$4)) and	US-PGPUB	2000,02,11 105
İ		(via trench hole recess)) and (insulat\$3	05 10105	
		dielectric)) and (pr photo?resist		
[		photoresist resist)) and (copper Cu		
		aluminum Al)) and wir\$3) and resin) and	]	
		circuit) and (cover\$3 encapsulat\$3)) and		
		((etch\$3 pattern\$4) near10 (copper Cu		
		conduct\$3))) and wir\$3) and bond\$3		
_	2660	(((((((((((conduct\$3 copper) near5 (foil	USPAT:	2003/02/11 17:42
	2000	sheet layer) ) and (etch\$3 pattern\$4)) and	US-PGPUB	2003/02/11 17:42
		(via trench hole recess)) and (insulat\$3	OD TGLOD	
	'	dielectric)) and (pr photo?resist		
	İ	photoresist resist)) and (copper Cu		
		aluminum Al)) and wir\$3) and resin) and		
		circuit) and (cover\$3 encapsulat\$3)) and		
		((etch\$3 pattern\$4) near10 (copper Cu		
		conduct\$3))) and wir\$3) and (die bond\$3)		
L	L	conductabili and Arrabi and (dre boudab)	L	

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